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Neoconix Announces High Density 0.8mm Array Pitch Availability

SUNNYVALE, CA May 25, 2007 – Neoconix today announced availability of a new 0.8mm pitch offering of its PCBeam™ interconnect technology for area-array applications.

Neoconix has overcome the industry challenge of sub-1.0mm array pitch by utilizing an innovative manufacturing approach based largely on PCB fabrication techniques. Neoconix precisely defines its contact element arrays using photolithography-based methods. The contact arrays are then integrated onto an FR-4 substrate using proprietary batch processing methods. Since the contacts are effectively embedded onto the substrate, they can be positioned in close proximity to each other with excellent dimensional scalability. Meanwhile, each contact element is all-metal so it maintains the excellent spring properties and contact wipe that are critical to a reliable interface.

Neoconix's approach is in contrast to traditional connector manufacturing in which individual contact elements are stamped and stitched into tiny thin-walled openings within a molded housing. As pitches shrink below 1.0mm, such approaches are challenged by susceptibility to breakage of thin-walled housings, dislodging of the loose contacts, and difficulty in maintaining true position.

“There is a gap between the 0.8mm pitch performance demands we see from our customers and what is currently available with traditional manufacturing,” said Larry Dittmann, EVP Business Development. “This new Neoconix capability closes that gap, and I am very pleased with the initial response we are receiving.”

Neoconix's new offering comes in response to growing challenges to increase density. Wider busses, increased power demands, and functional integration require more signal and power lines per device. At the same time, product sizes are shrinking and PCB real estate is becoming much more limited.

Neoconix adds the 0.8mm array pitch to its standard offerings that also include 1.27mm array pitch, 1.0mm array pitch, and 0.5 row pitch. Neoconix also offers interposers and connectors for custom and irregular contact patterns. Typical applications include interconnects for mating package-to-board, board-to-board, and flex-to-board, as well as embedded contacts for module substrates and flex circuits.

About Neoconix: Neoconix, Inc. blazes the path of least resistance between electronic devices with innovative interconnect solutions. The company leverages proprietary technologies and unique manufacturing processes to deliver optimized electrical interconnection solutions that greatly improve the cost and performance of electronic systems. For more information, visit www.neoconix.com.